

Product Change Notification / NTDO-04BHBR022

n	^	+	^		
IJ	a	ı	H	•	

09-Mar-2022

Product Category:

Closed Fan Controllers, Current And Power Measurement ICs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4782 Final Notice: Qualification of MTAI as an additional assembly site for selected SMSC EMC1701, EMC1702, EMC2103 and EMC2303 device families available in 12L QFN (4x4x0.9mm) package assembled at ASE assembly site.

Affected CPNs:

NTDO-04BHBR022_Affected_CPN_03092022.pdf NTDO-04BHBR022_Affected_CPN_03092022.csv

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of MTAI as an additional assembly site for selected SMSC EMC1701, EMC1702, EMC2103 and EMC2303 device families available in 12L QFN (4x4x0.9mm) package assembled at ASE assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	Microchip Technology Thailand (HQ) MTAI			
Wire Material	Au / PdCu	Au / PdCu	Au			
Die Attach Material	EN-4900F	EN-4900F	QMI-519			
Molding Compound Material	G631H	G631H	G700LTD			
Lead-Frame Material	A194	A194	A194			
Lead-Frame Paddle Size	91 x 91 mm	91 x 91 mm	91 x 91 mm			
Lead-Frame Lead-lock	No	No	Yes			
DAP Surface Prep	Ag ring plating	Ag ring plating	Ag ring plating			

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:March 07, 2022 (date code: 2211)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2021				February 2022			March 2022							
Workweek	4 5	4 6	4 7	4 8	4 9	→	0 6	0 7	0 8	0 9	1 0	1 1	1 2	1 2	1 4
Initial PCN Issue Date			Х												
Qual Report Availability									Х						
Final PCN Issue Date									Х						
Estimated First Ship Date												Х			

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

November 17, 2021: Issued initial notification.

February 11, 2022: Issued final notification. Corrected the lead frame lead-lock for ASE in Post Change column from Yes to No. Provided estimated first ship date to be March 07, 2022.

March 09, 2022: Re-issued final notification. Attached qualification report and updated the timetable summary.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_NTDO-04BHBR022_Pre_and_Post_Change_Summary.pdf PCN_NTDO-04BHBR022_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

NTDO-04BHBR022 - CCB 4782 Final Notice: Qualification of MTAI as an additional assembly site for selected SMSC EMC1701, EMC1702, EMC2103 and EMC2303 device families available in 12L QFN (4x4x0.9mm) package assembled at ASE assembly site.

Affected Catalog Part Numbers (CPN)

EMC1701-1-KP-TR

EMC1702-1-KP-TR

EMC2103-1-KP-TR

EMC2303-1-KP-TR

Date: Tuesday, March 08, 2022